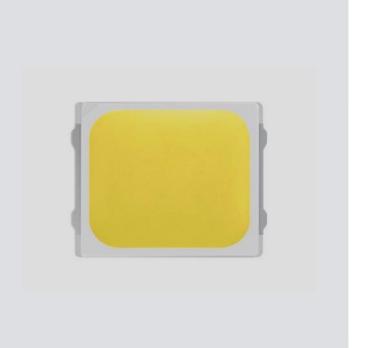
Middle Power LED Series 2835 0.5W Room Temp

LM281B+ SErank



# Designed for better Im/\$ (Ambient, Linear)







## **Features & Benefits**

- 0.5W Class mid power LED
- Standard form factor for design flexibility (2.8 × 3.5 mm)

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## 1. Characteristics

## a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	Ta	-40 ~ +85	°C	-
Storage Temperature	$T_{stg}$	-40 ~ +85	°C	-
LED Junction Temperature	Tj	115	°C	-
Forward Current	l <sub>F</sub>	160	mA	-
Peak Pulsed Forward Current	l <sub>Ep</sub>	300	mA	Duty 1/10, pulse width 10ms
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	2	kV	-

#### Note:

Proper current derating must be observed to maintain junction temperature below the maximum at all time.

It is recommended minimum current 10mA in order to avoid un-even brightness, and may vary depending on circuit configuration.

ltem	Unit	Rank	Bin	Min.	Тур.	Max.
			A1	2.8		2.9
		WA	A2	2.9		3.0
Conversit Vallage AVC	V	or ·····	A3	3.0		3.1
Forward Voltage (VF)	V		A4	3.1		3.2
		WN	A1	2.8		2.9
		or ·····	A2	2.9		3.0
Octor Productor Index (Pr)		5		80	_	_
Color Rendering Index (Ra)		7		90		
Special CRI (R9)	For Ra 90			50		
Thermal Resistance (junction to solder point)	°C/W			_	25	_
Beam Angle	0			_	120	_

## Note:

Samsung maintains measurement tolerance of: forward voltage =  $\pm 0.1$  V, CRI =  $\pm 3$ , R9 =  $\pm 6.5$ 

## c) Electro-optical Characteristics (I<sub>F</sub> = 150 mA, $T_s$ = 25 °C)

ltem	CRI (R <sub>a</sub> )	Nominal	Bin	150	mA
item	Min.	CCT (K)	DIII	Min.	Max.
		2700	SE	62.5	66.5
		3000	SE	64.5	68.5
		3500	SE	65.5	69.5
	80	4000	SE	68.0	72.0
		5000	SE	69.0	73.0
		5700	SE	68.5	72.5
Luminous Flux (Фv)		6500	SE	68.0	72.0
Laninous Flax (\Psi v)		2700	SE	52.5	56.5
		3000	SE	54.0	58.0
		3500	SE	55.0	59.0
	90	4000	SE	57.0	61.0
		5000	SE	58.0	62.0
		5700	SE	57.5	61.5
		6500	SE	57.0	61.0

## Note:

Samsung maintains measurement tolerance of: forward voltage =  $\pm 0.1$ V, luminous flux =  $\pm 5$  %, CRI =  $\pm 3$ 



## 2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	Р	M	W	н	1	2	2	8	F	D	5	W	Α	R	0	S	Е

Digit	PKG Information	Code			Specification			
1 2 3	Samsung Package Middle Power	SPM	Middle po	Middle power				
4 5	Color	WH	White	White				
6	Product Version	1	Without 2	Zener				
7 8 9	Form Factor	228	2.8 x 3.5	x 0.7 mm;	2 pads			
10	Sorting Current (mA)	F	150 mA					
11	Chromaticity Coordinates	D	ANSI Sta	ndard				
40	ODI	5	Min. 80					
12	CRI	7	Min. 90					
		WA or WK	2.8~3.2	Bin code	A1 2.8 ~ 2.9 A2 2.9 ~ 3.0 A3 3.0 ~ 3.1 A4 3.1 ~ 3.2			
13 14	Forward Voltage (V)		WA: 4,00	WA: 4,000ea per reel ,WK: 16,000ea per reel				
		WN	2.8~3.0	Bin code	A1 2.8 ~ 2.9 A2 2.9 ~ 3.0			
		WM	WN : 4,0	00ea per r	reel ,WM : 16,000ea per reel			
		W☆	2700		W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG WN, WP, WQ, WR, WS, WT, WU			
		V☆	3000		V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG VN, VP, VQ, VR, VS, VT, VU			
		U☆	3500		U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG UN, UP, UQ, UR, US, UT, UU			
15 16	CCT (K)	T☆	4000	Bin Code:	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG TN, TP, TQ, TR, TS, TT, TU			
15 16	CCT (K)	R☆	5000		R1, R2, R3, R4, R5, R6, R7, R8, R9,RA,RB,RC,RD,RE,RF,RG RN, RP, RQ, RR, RS, RT, RU			
		Q☆	5700		Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9,QA,QB,QC,QD,QE,QF,QG QN, QP, QQ, QR, QS, QT, QU			
		P☆	6500		P1, P2, P3, P4, P5, P6, P7, P8, P9,PA,PB,PC,PD,PE,PF,PG PN, PP, PQ, PR, PS, PT, PU			
			☆: "0" (Whole bin), "M" (Quarter bin), "K" (K Kitting bin), "Y"(Y Kitting bin) or "U" (Mac3 only)					
17 18	Luminous Flux	SE	Bin SE Code					

## a) Luminous Flux Bins (I<sub>F</sub> = 150 mA, $T_s$ = 25°C)

CRI (R <sub>a</sub> ) Min	Nominal CCT (K)	Product Code	Flux Bin	Flux Range (Ф., Im)
	2700	SPMWH1228FD5WAW☆SE	SE	62.5 ~ 66.5
	3000	SPMWH1228FD5WAV☆SE	SE	64.5 ~ 68.5
	3500	SPMWH1228FD5WAU☆SE	SE	65.5 ~ 69.5
80	4000	SPMWH1228FD5WAT☆SE	SE	68.0 ~ 72.0
	5000	SPMWH1228FD5WAR☆SE	SE	69.0 ~ 73.0
	5700	SPMWH1228FD5WAQ☆SE	SE	68.5 ~ 72.5
	6500	SPMWH1228FD5WAP☆SE	SE	68.0 ~ 72.0
	2700	SPMWH1228FD7WAW☆SE	SE	52.5 ~ 56.5
	3000	SPMWH1228FD7WAV☆SE	SE	54.0 ~ 58.0
	3500	SPMWH1228FD7WAU☆SE	SE	55.0 ~ 59.0
90	4000	SPMWH1228FD7WAT☆SE	SE	57.0 ~ 61.0
	5000	SPMWH1228FD7WAR☆SE	SE	58.0 ~ 62.0
	5700	SPMWH1228FD7WAQ☆SE	SE	57.5 ~ 61.5
	6500	SPMWH1228FD7WAP☆SE	SE	57.0 ~ 61.0

## Note:

"☆" can be "0" (Whole bin), "M" (Quarter bin), "K" (K Kitting bin), "Y"(Y Kitting bin) or "U" (Mac3 only) of the color binning



## b) Kitting rule

## 1) K Kitting bin Concept

- 1. Under agreement between customer and SAMSUNG ELECTRONICS, SAMSUNG can supply kitting bin (VF, Color, Im).
- 2. A forward voltage (VF) of kitting bin is combined by a pair of same VF rank such as (A1+A1), (A2+A2), (A3+A3) or (A4+A4)
- 3. A Chromaticity Coordinates of kitting bin is mixed by kitting procedure.(below kitting simulation)

## [Kitting example]

D	E	F	O
9	А	В	С
5	6	7	8
1	2	3	4

## [Binning Information]

	Bin #1	Bin #2
	A1	A1
VF	A2	A2
VF	A3	A3
	A4	A4
	1, 2, 5 bin	C, F, G bin
CIE	6, 7, A, B bin	6, 7, A, B bin
	3, 4, 8 bin	9, D, E bin

## 2) Y Kitting bin Concept

- 4. Under agreement between customer and SAMSUNG ELECTRONICS, SAMSUNG can supply kitting bin (VF, Color, Im).
- 5. A forward voltage (VF) of kitting bin is combined by a pair of same VF rank such as (A1+A1), (A2+A2), (A3+A3) or (A4+A4)
- 6. A Chromaticity Coordinates of kitting bin is mixed by kitting procedure.(below kitting simulation)

## [Kitting example]



## [Binning Information]

	Bin #1	Bin #2
	A1	A1
VF	A2	A2
VF	A3	A3
	A4	A4
	U	U
CIE	N	R
CIE	Р	S
	Q	Т

## c) Color Bins (I<sub>F</sub> = 150 mA, $T_s$ = 25 °C)

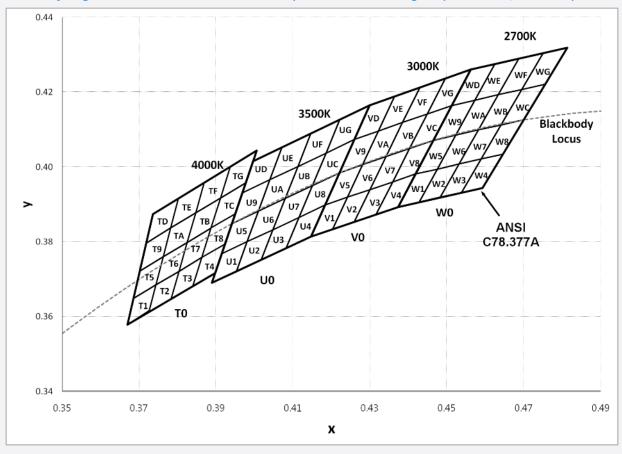
CRI (R <sub>a</sub> ) Min.	Nominal CCT (K)	Product Code	Color Rank	Chromaticity Bins
		SPMWH1228FD★WAW0SE	W0 (Whole bin)	W1,W2,W3,W4,W5,W6,W7,W8,W9,WA,WB,WC,WD,WE,WF,WG
		SPMWH1228FD★WAWMSE	WM (Quarter bin)	W6, W7, WA, WB
	2700	SPMWH1228FD★WAWKSE	WK (K Kitting bin)	W1,W2,W3,W4,W5,W6,W7,W8,W9,WA,WB,WC,WD,WE,WF,WG
		SPMWH1228FD★WAWUSE	WU (Mac3 Only)	WU
		SPMWH1228FD★WAWYSE	WY (Y Kitting bin)	WN, WP, WQ, WR, WS, WT, WU
		SPMWH1228FD★WAV0SE	V0 (Whole bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
		SPMWH1228FD★WAVMSE	VM (Quarter bin)	V6, V7, VA, VB
	3000	SPMWH1228FD★WAVKSE	VK (K Kitting bin)	V1, V2, V3, V4, V5, V6, V7, V8,V9, VA, VB, VC, VD, VE, VF, VG
	****	SPMWH1228FD★WAVUSE	VU (Mac3 Only)	VU
	****	SPMWH1228FD★WAVYSE	VY (Y Kitting bin)	VN, VP, VQ, VR, VS, VT, VU
		SPMWH1228FD★WAU0SE	U0 (Whole bin)	U1, U2, U3, U4, U5, U6, U7, U8,U9, UA, UB, UC, UD, UE, UF, UG
		SPMWH1228FD★WAUMSE	UM (Quarter bin)	U6, U7, UA, UB
	3500	SPMWH1228FD★WAUKSE	UK (K Kitting bin)	U1, U2, U3, U4, U5, U6, U7, U8,U9, UA, UB, UC, UD, UE, UF, UG
		SPMWH1228FD★WAUUSE	UU (Mac3 Only)	UU
		SPMWH1228FD★WAUYSE	UY (Y Kitting bin)	UN, UP, UQ, UR, US, UT, UU
		SPMWH1228FD★WAT0SE	T0 (Whole bin)	T1, T2, T3, T4, T5, T6, T7, T8,T9, TA, TB, TC, TD, TE, TF, TG
00		SPMWH1228FD★WATMSE	TM (Quarter bin)	T6, T7, TA, TB
80 or	4000	SPMWH1228FD★WATKSE	TK (K Kitting bin)	T1, T2, T3, T4, T5, T6, T7, T8,T9, TA, TB, TC, TD, TE, TF, TG
90		SPMWH1228FD★WATUSE	TU (Mac3 Only)	TU
		SPMWH1228FD★WATYSE	TY (Y Kitting bin)	TN, TP, TQ, TR, TS, TT, TU
		SPMWH1228FD★WAR0SE	R0 (Whole bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9RA,RB,RC,RD,RE,RF,RG
		SPMWH1228FD★WARMSE	RM (Quarter bin)	R6, R7, RA, RB
	5000	SPMWH1228FD★WARKSE	RK (K Kitting bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9RA,RB,RC,RD,RE,RF,RG
		SPMWH1228FD★WARUSE	RU (Mac3 Only)	RU
		SPMWH1228FD★WARYSE	RY (Y Kitting bin)	RN, RP, RQ, RR, RS, RT, RU
		SPMWH1228FD★WAQ0SE	Q0 (Whole bin)	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9QA,QB,QC,QD,QE,QF,QG
		SPMWH1228FD★WAQMSE	QM (Quarter bin)	Q6, Q7, QA, QB
	5700	SPMWH1228FD★WAQKSE	QK (K Kitting bin)	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9QA,QB,QC,QD,QE,QF,QG
		SPMWH1228FD★WAQUSE	QU (Mac3 Only)	QU
		SPMWH1228FD★WAQYSE	QY (Y Kitting bin)	QN, QP, QQ, QR, QS, QT, QU
		SPMWH1228FD★WAP0SE	P0 (Whole bin)	P1, P2, P3, P4, P5, P6, P7, P8, P9PA,PB,PC,PD,PE,PF,PG
		SPMWH1228FD★WAPMSE	PM (Quarter bin)	P6, P7, PA, PB
	6500	SPMWH1228FD★WAPKSE	PK (K Kitting bin)	P1, P2, P3, P4, P5, P6, P7, P8, P9PA,PB,PC,PD,PE,PF,PG
	***	SPMWH1228FD★WAPUSE	PU (Mac3 Only)	PU
		SPMWH1228FD★WAPYSE	PY (Y Kitting bin)	PN, PP, PQ, PR, PS, PT, PU

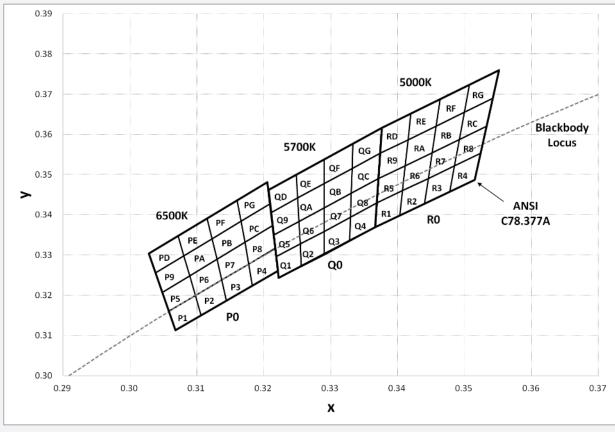
**Note:** "★" can be "5" (Ra80) or "7" (Ra90)

## d) Voltage Bins (I<sub>F</sub> = 150 mA, $T_s$ = 25 °C)

CRI (R₃) Min.	Nominal CCT (K)	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
				A1	2.8 ~ 2.9
			WA	A2	2.9 ~ 3.0
-	-	-	or	А3	3.0 ~ 3.1
			***	A4	3.1 ~ 3.2
			WN	A1	2.8 ~ 2.9
-	-	-	or	A2	2.9 ~ 3.0

## e) Chromaticity Region & Coordinates for whole bin or quarter bin or K kitting bin ( $I_F$ = 150 mA, $T_s$ = 25 °C)





Region	CIEx	CIE y Region		CIE x	CIE y
		W rank	(2700 K)		
	0.4373	0.3893		0.4465	0.4071
W1	0.4418	0.3981	14/0	0.4513	0.4164
VVI	0.4475	0.3994	W9	0.4573	0.4178
	0.4428	0.3906		0.4523	0.4085
	0.4428	0.3906		0.4523	0.4085
14/0	0.4475	0.3994	14/4	0.4573	0.4178
W2	0.4532	0.4008	WA	0.4634	0.4193
	0.4483	0.3919		0.4582	0.4099
	0.4483	0.3919		0.4582	0.4099
14/0	0.4532	0.4008	WD	0.4634	0.4193
W3	0.4589	0.4021	WB	0.4695	0.4207
	0.4538	0.3931		0.4641	0.4112
	0.4538	0.3931		0.4641	0.4112
10/4	0.4589	0.4021	WC	0.4695	0.4207
W4	0.4646	0.4034		0.4756	0.4221
	0.4593	0.3944		0.4700	0.4126
	0.4418	0.3981		0.4513	0.4164
)A/5	0.4465	0.4071		0.4562	0.4260
W5	0.4523	0.4085	WD	0.4624	0.4274
	0.4475	0.3994		0.4573	0.4178
	0.4475	0.3994		0.4573	0.4178
1440	0.4523	0.4085	10/5	0.4624	0.4274
W6	0.4582	0.4099	WE	0.4687	0.4289
	0.4532	0.4008		0.4634	0.4193
	0.4532	0.4008		0.4634	0.4193
14.7	0.4582	0.4099	14/5	0.4687	0.4289
W7	0.4641	0.4112	WF	0.4750	0.4304
	0.4589	0.4021		0.4695	0.4207
	0.4589	0.4021		0.4695	0.4207
	0.4641	0.4112		0.4750	0.4304
W8	0.4700	0.4126	WG	0.4813	0.4319
	0.4646	0.4034		0.4756	0.4221

Region	CIEx	CIE y Region		CIEx	CIE y
		V rank	(3000 K)		•
	0.4147	0.3814		0.4221	0.3984
	0.4183	0.3898		0.4259	0.4073
V1	0.4242	0.3919	V9	0.4322	0.4096
	0.4203	0.3833		0.4281	0.4006
	0.4203	0.3833		0.4281	0.4006
\ /O	0.4242	0.3919	1/0	0.4322	0.4096
V2	0.4300	0.3939	VA	0.4385	0.4119
	0.4259	0.3853		0.4342	0.4028
	0.4259	0.3853		0.4342	0.4028
) /O	0.4300	0.3939		0.4385	0.4119
V3	0.4359	0.3960	VB	0.4449	0.4141
	0.4316	0.3873		0.4403	0.4049
	0.4316	0.3873		0.4403	0.4049
	0.4359	0.3960	VC	0.4449	0.4141
V4	0.4418	0.3981		0.4513	0.4164
	0.4373	0.3893		0.4465	0.4071
	0.4183	0.3898		0.4259	0.4073
	0.4221	0.3984		0.4299	0.4165
V5	0.4281	0.4006	VD	0.4364	0.4188
	0.4242	0.3919		0.4322	0.4096
	0.4242	0.3919		0.4322	0.4096
\ /O	0.4281	0.4006		0.4364	0.4188
V6	0.4342	0.4028	VE	0.4430	0.4212
	0.4300	0.3939		0.4385	0.4119
	0.4300	0.3939		0.4385	0.4119
	0.4342	0.4028		0.4430	0.4212
V7	0.4403	0.4049	VF	0.4496	0.4236
	0.4359	0.3960		0.4449	0.4141
	0.4359	0.3960		0.4449	0.4141
1/0	0.4403	0.4049	\/C	0.4496	0.4236
V8	0.4465	0.4071	VG	0.4562	0.4260
	0.4418	0.3981		0.4513	0.4164

Region	CIEx	CIE y Region		CIE x	CIE y
		U rank	(3500 K)		
	0.3889	0.3690		0.3941	0.3848
114	0.3915	0.3768	110	0.3968	0.3930
U1	0.3981 0.3800	U9	0.4040	0.3966	
	0.3953	0.3720		0.4010	0.3882
	0.3953	0.3720		0.4010	0.3882
1.10	0.3981	0.3800		0.4040	0.3966
U2	0.4048	0.3832	UA	0.4113	0.4001
	0.4017	0.3751		0.4080	0.3916
	0.4017	0.3751		0.4080	0.3916
1.10	0.4048	0.3832		0.4113	0.4001
U3	0.4116	0.3865	UB	0.4186	0.4037
	0.4082	0.3782		0.4150	0.3950
	0.4082	0.3782		0.4150	0.3950
	0.4116	0.3865	UC	0.4186	0.4037
U4	0.4183	0.3898		0.4259	0.4073
	0.4147	0.3814		0.4221	0.3984
	0.3915	0.3768		0.3968	0.3930
	0.3941	0.3848		0.3996	0.4015
U5	0.4010	0.3882	UD	0.4071	0.4052
	0.3981	0.3800		0.4040	0.3966
	0.3981	0.3800		0.4040	0.3966
	0.4010	0.3882		0.4071	0.4052
U6	0.4080	0.3916	UE	0.4146	0.4089
	0.4048	0.3832		0.4113	0.4001
	0.4048	0.3832		0.4113	0.4001
	0.4080	0.3916		0.4146	0.4089
U7	0.4150	0.3950	UF	0.4222	0.4127
	0.4116	0.3865		0.4186	0.4037
	0.4116	0.3865		0.4186	0.4037
	0.4150	0.3950		0.4222	0.4127
U8	0.4221	0.3984	UG	0.4299	0.4165
	0.4183	0.3898		0.4259	0.4073

Region	CIEx	CIE y	Region	CIEx	CIE y
		T rank	(4000 K)	•	•
	0.3670	0.3578		0.3702	0.3722
	0.3726	0.3612	T0	0.3763	0.3760
T1	0.3744	0.3685	T9	0.3782	0.3837
	0.3686	0.3649		0.3719	0.3797
	0.3726	0.3612		0.3763	0.3760
T0	0.3783	0.3646	Τ.	0.3825	0.3798
T2	0.3804	0.3721	TA	0.3847	0.3877
	0.3744	0.3685		0.3782	0.3837
	0.3783	0.3646		0.3825	0.3798
	0.3840	0.3681		0.3887	0.3836
Т3	0.3863	0.3758	TB	0.3912	0.3917
	0.3804	0.3721		0.3847	0.3877
	0.3840	0.3681		0.3887	0.3837
T4	0.3898	0.3716	тс	0.3950	0.3875
T4	0.3924	0.3794		0.3978	0.3958
	0.3863	0.3758		0.3912	0.3917
	0.3686	0.3649		0.3719	0.3797
	0.3744	0.3685	TD	0.3782	0.3837
T5	0.3763	0.3760	TD	0.3802	0.3916
	0.3702	0.3722		0.3736	0.3874
	0.3744	0.3685		0.3782	0.3837
TO	0.3804	0.3721		0.3847	0.3877
T6	0.3825	0.3798	TE	0.3869	0.3958
	0.3763	0.3760		0.3802	0.3916
	0.3804	0.3721		0.3847	0.3877
T-7	0.3863	0.3758	TF	0.3912	0.3917
T7	0.3887	0.3836	TF	0.3937	0.4001
	0.3825	0.3798		0.3869	0.3958
	0.3863	0.3758		0.3912	0.3917
то	0.3924	0.3794	TO	0.3978	0.3958
T8	0.3950	0.3875	TG	0.4006	0.4044
	0.3887	0.3836		0.3937	0.4001

Region	CIEx	CIE y Region		CIE x	CIE y
		R rank	(5000 K)		
	0.3366	0.3369		0.3374	0.3554
D4	0.3369	0.3431	DO	0.3371	0.3493
R1	0.3407	0.3460	R9	0.3411	0.3522
	0.3403	0.3398		0.3415	0.3587
	0.3403	0.3398		0.3415	0.3587
DO	0.3407	0.3460		0.3411	0.3522
R2	0.3446	0.3491	RA	0.3451	0.3554
	0.3440	0.3427	•	0.3457	0.3621
	0.3446	0.3491		0.3451	0.3554
<b>D</b> 0	0.3440	0.3427		0.3457	0.3621
R3	0.3477	0.3458	RB	0.3500	0.3655
	0.3485	0.3522	•	0.3492	0.3587
	0.3485	0.3522		0.3492	0.3587
54	0.3477	0.3458	RC	0.3500	0.3655
R4	0.3514	0.3487		0.3542	0.3690
	0.3524	0.3554		0.3533	0.3620
	0.3371	0.3493		0.3376	0.3616
5.5	0.3369	0.3431		0.3374	0.3554
R5	0.3407	0.3460	RD	0.3415	0.3587
	0.3411	0.3522		0.3420	0.3652
	0.3407	0.3460		0.3415	0.3587
50	0.3411	0.3522		0.3420	0.3652
R6	0.3451	0.3554	RE	0.3463	0.3687
	0.3446	0.3491		0.3457	0.3621
	0.3446	0.3491		0.3457	0.3621
D-7	0.3451	0.3554		0.3463	0.3687
R7	0.3492	0.3587	RF	0.3507	0.3724
	0.3485	0.3522		0.3500	0.3655
	0.3485	0.3522		0.3500	0.3655
F.0	0.3492	0.3587		0.3507	0.3724
R8	0.3533	0.3620	RG	0.3551	0.3760
	0.3524	0.3554		0.3542	0.3690

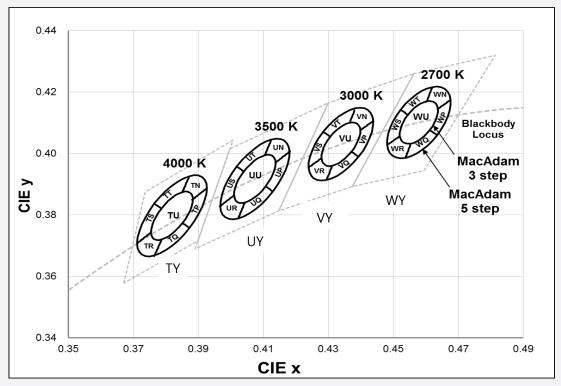
Region	CIEx	CIE y	Region	CIEx	CIE y
		Q rank	(5700 K)		
	0.3218	0.3298		0.3211	0.3407
01	0.3222	0.3243	00	0.3215	0.3353
Q1	0.3258	0.3275	Q9	0.3254	0.3388
	0.3256	0.3331		0.3252	0.3444
	0.3256	0.3331		0.3252	0.3444
00	0.3258	0.3275	0.4	0.3254	0.3388
Q2	0.3294	0.3306	QA	0.3293	0.3423
	0.3294	0.3364		0.3293	0.3481
	0.3294	0.3364		0.3293	0.3481
	0.3294	0.3306	0.5	0.3293	0.3423
Q3	0.3330	0.3338	QB	0.3332	0.3458
	0.3331	0.3398		0.3333	0.3518
	0.3331	0.3398		0.3333	0.3518
	0.3330	0.3338	QC	0.3332	0.3458
Q4	0.3366	0.3369		0.3371	0.3493
	0.3369	0.3431		0.3374	0.3554
	0.3215	0.3353		0.3207	0.3462
	0.3218	0.3298		0.3211	0.3407
Q5	0.3256	0.3331	QD	0.3252	0.3444
	0.3254	0.3388		0.3250	0.3501
	0.3254	0.3388		0.3250	0.3501
	0.3256	0.3331		0.3252	0.3444
Q6	0.3294	0.3364	QE	0.3293	0.3481
	0.3293	0.3423		0.3292	0.3539
	0.3293	0.3423		0.3292	0.3539
	0.3294	0.3364	6-	0.3293	0.3481
Q7	0.3331	0.3398	QF	0.3333	0.3518
	0.3332	0.3458		0.3334	0.3578
	0.3332	0.3458		0.3334	0.3578
	0.3331	0.3398		0.3333	0.3518
Q8	0.3369	0.3431	QG	0.3374	0.3554
	0.3371	0.3493		0.3376	0.3616

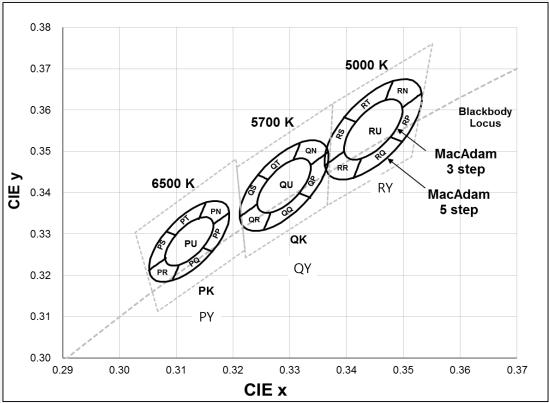
Region	CIEx	CIE y	Region	CIE x	CIE y
		Prank	(6500 K)	·	
	0.3068	0.3113		0.3048	0.3207
D4	0.3106	0.3150	DO	0.3089	0.3249
P1	0.3098	0.3199	- P9	0.3080	0.3298
	0.3058 0.3160	0.3038	0.3256		
	0.3106	0.3150		0.3089	0.3249
50	0.3144	0.3186		0.313	0.3290
P2	0.3137	0.3238	PA	0.3123	0.3341
	0.3098	0.3199		0.3080	0.3298
	0.3144	0.3186		0.3130	0.3290
50	0.3183	0.3224		0.3172	0.3332
P3	0.3177	0.3278	PB	0.3166	0.3384
	0.3137	0.3238	•	0.3123	0.3341
	0.3183	0.3224		0.3172	0.3332
	0.3221	0.3261	PC	0.3214	0.3373
P4	0.3218	0.3317		0.3210	0.3427
	0.3177	0.3278		0.3166	0.3384
	0.3058	0.3160		0.3038	0.3256
	0.3098	0.3199		0.3080	0.3298
P5	0.3089	0.3249	PD	0.3072	0.3348
	0.3048	0.3207	•	0.3028	0.3304
	0.3098	0.3199		0.3080	0.3298
	0.3137	0.3238		0.3123	0.3341
P6	0.3130	0.3290	· PE	0.3115	0.3391
	0.3089	0.3249	•	0.3072	0.3348
	0.3137	0.3238		0.3123	0.3341
	0.3177	0.3278		0.3166	0.3384
P7	0.3172	0.3332	PF	0.3160	0.3436
	0.313	0.3290		0.3115	0.3391
	0.3177	0.3278		0.3166	0.3384
	0.3218	0.3317		0.3210	0.3427
P8	0.3214	0.3373	PG	0.3206	0.3481
	0.3172	0.3332		0.3160	0.3436

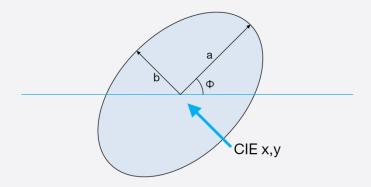
**Note:** Samsung maintains measurement tolerance of: Cx,  $Cy = \pm 0.005$ 



## f) Chromaticity Region & Coordinates for Y kitting bin or mac3 only bin ( $I_F$ = 150 mA, $T_s$ = 25 °C)

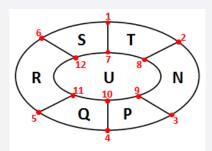






ManAdam	ССТ	Cent	er point	Major-axis	Minor-axis	Rotation
MacAdam	(K)	CIE x	CIE y	а	b	Ф
	2700	0.4578	0.4101	0.0081	0.0042	53.70
	3000	0.4338	0.4030	0.0083	0.0041	53.22
	3500	0.4073	0.3917	0.0093	0.0041	54.00
3 step	4000	0.3818	0.3797	0.0094	0.0040	53.72
	5000	0.3447	0.3553	0.0082	0.0035	59.62
	5700	0.3287	0.3417	0.0075	0.0032	59.10
	6500	0.3123	0.3282	0.0067	0.0029	58.57
	2700	0.4578	0.4101	0.0135	0.0070	53.70
	3000	0.4338	0.4030	0.0138	0.0068	53.22
	3500	0.4073	0.3917	0.0155	0.0068	54.00
5 step	4000	0.3818	0.3797	0.0157	0.0067	53.72
	5000	0.3447	0.3553	0.0137	0.0058	59.62
	5700	0.3287	0.3417	0.0125	0.0053	59.10
	6500	0.3123	0.3282	0.0112	0.0048	58.57

**Note:** Samsung maintains measurement tolerance of: Cx,  $Cy = \pm 0.005$ 



ССТ	Region	CIE x	CIEy	ССТ	Region	CIEx	CIE y	ССТ	Region	CIE x	CIE y
	1	0.4521	0.4142		1	0.4283	0.4071		1	0.4018	0.3957
	2	0.4619	0.4216		2	0.4382	0.4146		2	0.4125	0.4046
	3	0.4675	0.4175		3	0.4437	0.4105		3	0.418	0.4005
	4	0.4634	0.4059		4	0.4393	0.3989		4	0.4128	0.3877
	5	0.4537	0.3986		5	0.4293	0.3913		5	0.4022	0.3788
070016	6	0.4481	0.4028	200014	6	0.4239	0.3954	OF OOK	6	0.3966	0.3828
2700K	7	0.4544	0.4126	3000K	7	0.4305	0.4054	3500K	7	0.404	0.3941
	8	0.4603	0.417		8	0.4364	0.41		8	0.4104	0.3994
	9	0.4636	0.4145		9	0.4397	0.4075		9	0.4137	0.397
	10	0.4612	0.4076		10	0.4371	0.4005		10	0.4106	0.3893
	11	0.4553	0.4032		11	0.4311	0.396		11	0.4042	0.384
	12	0.452	0.4057		12	0.4279	0.3984		12	0.4009	0.3864
	1	0.3764	0.3837		1	0.3397	0.3583		1	0.3242	0.3445
	2	0.3871	0.3926		2	0.3482	0.367		2	0.332	0.3524
	3	0.3925	0.3887		3	0.3532	0.364		3	0.3365	0.3496
	4	0.3872	0.3758		4	0.3497	0.3524		4	0.3333	0.339
	5	0.3765	0.3668		5	0.3412	0.3436		5	0.3254	0.331
4000K	6	0.3711	0.3707	5000K	6	0.3362	0.3465	5700K	6	0.3209	0.3338
4000K	7	0.3786	0.3821	5000K	7	0.3417	0.3571	3700K	7	0.326	0.3434
	8	0.385	0.3874		8	0.3468	0.3623		8	0.3307	0.3481
	9	0.3882	0.3851		9	0.3498	0.3605		9	0.3334	0.3464
	10	0.385	0.3773		10	0.3477	0.3535		10	0.3314	0.3401
	11	0.3786	0.372		11	0.3426	0.3483		11	0.3267	0.3353
	12	0.3754	0.3743		12	0.3396	0.35		12	0.324	0.3369

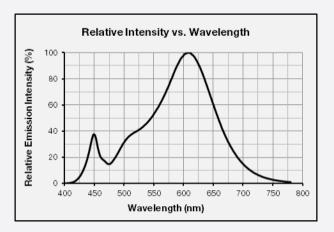
ССТ	Region	CIEx	CIE y
	1	0.3082	0.3307
	2	0.3153	0.3377
	3	0.3194	0.3352
	4	0.3164	0.3257
	5	0.3093	0.3187
CEOOK	6	0.3052	0.3212
6500K	7	0.3098	0.3297
	8	0.3141	0.3339
	9	0.3166	0.3324
	10	0.3148	0.3267
	11	0.3105	0.3225
	12	0.308	0.324

**Note:** Samsung maintains measurement tolerance of: Cx,  $Cy = \pm 0.005$ 

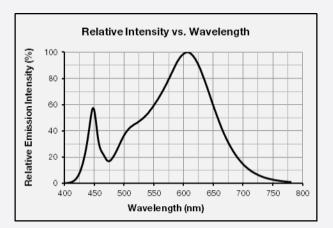
## 3. Typical Characteristics Graphs

## a) Spectrum Distribution ( $I_F = 150$ mA, $T_s = 25$ °C)

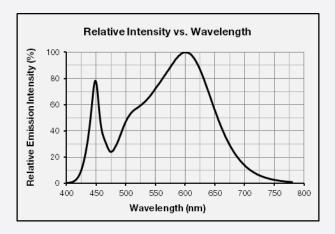
CCT: 2700 K (80 CRI)



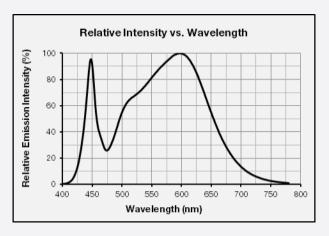
CCT: 3000 K (80 CRI)



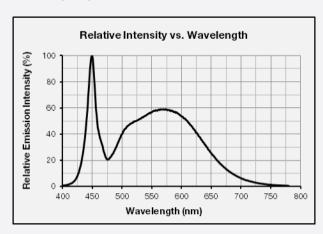
CCT: 3500 K (80 CRI)



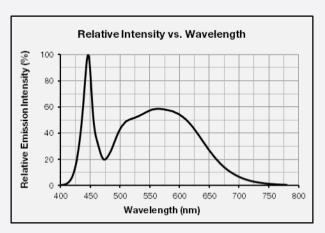
CCT: 4000 K (80 CRI)



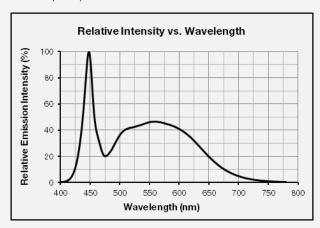
CCT: 5000 K (80 CRI)



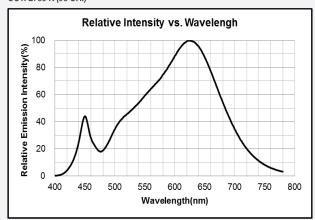
CCT: 5700 K (80 CRI)



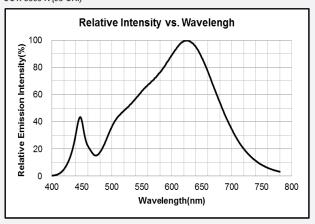
#### CCT: 6500 K (80 CRI)



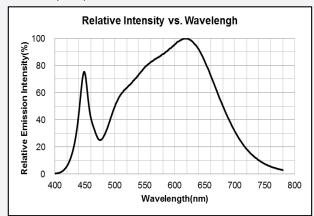
### CCT: 2700 K (90 CRI)



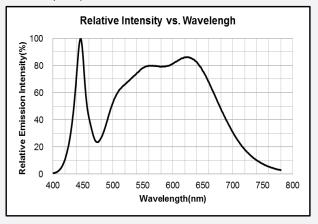
## CCT: 3000 K (90 CRI)



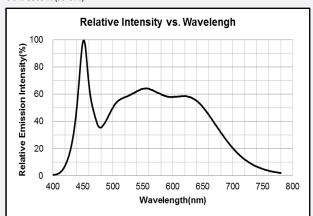
#### CCT: 3500 K (90 CRI)



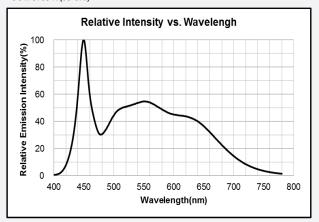
#### CCT: 4000 K (90 CRI)



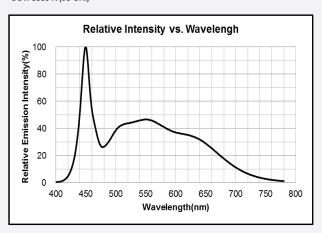
CCT: 5000 K (90 CRI)



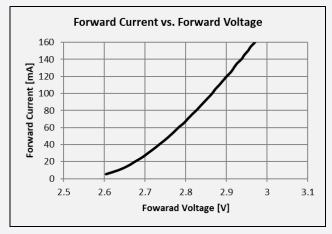
CCT: 5700 K (90 CRI)

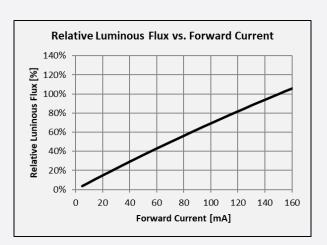


CCT: 6500 K (90 CRI)

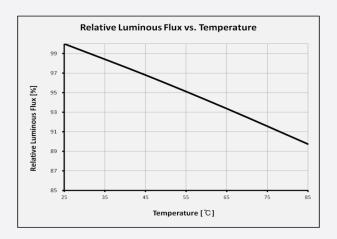


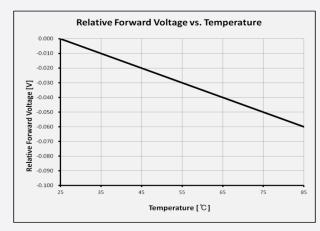
## b) Forward Current Characteristics (T<sub>s</sub> = 25 °C)



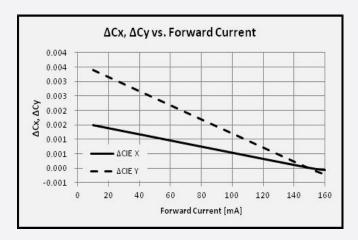


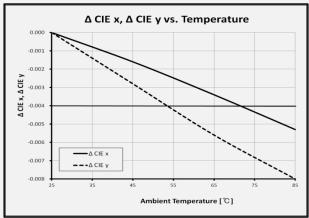
## c) Temperature Characteristics (I<sub>F</sub> = 150 mA)



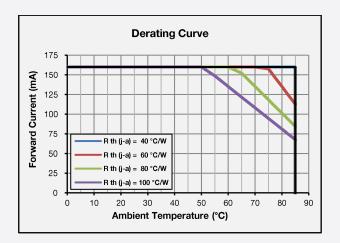


## d) Color Shift Characteristics (I<sub>F</sub> = 150 mA, T<sub>s</sub> = 25 °C)

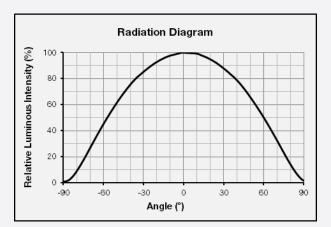




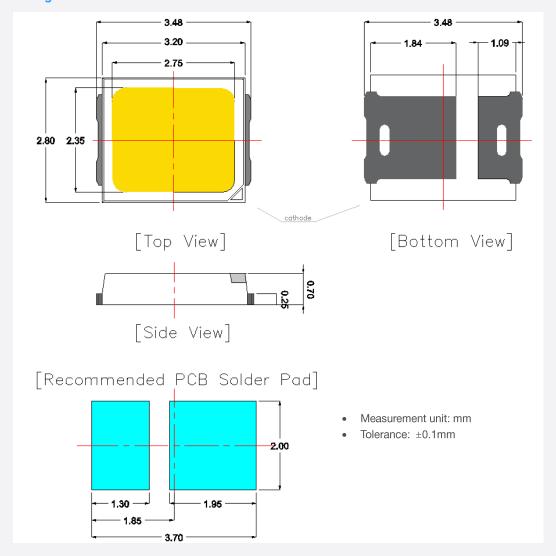
## e) Derating Curve



## f) Beam Angle Characteristics (I<sub>F</sub> = 150 mA, T<sub>s</sub> = 25 °C)



## 4. Outline Drawing & Dimension



#### Notes:

- 1) T<sub>s</sub> point and measurement method:
  - ① Measure one point at the cathode pad, if necessary remove PSR of PCB to reach T<sub>s</sub> point.
  - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

#### **Precautions:**

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

## 5. Reliability Test Items & Conditions

## a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample No.
Room Temperature Life Test	25 °C, DC Max Current	1000 h	22
High Temperature Life Test	85 °C, DC Max Current	1000 h	22
High Temperature Humidity Life Test	85 °C, 85 % RH DC Max Current	1000 h	22
Low Temperature Life Test	-40 °C, DC Max Current	1000 h	22
Powered Temperature Cycle Test	-45 °C $\sim$ 85 °C, each $$ 20 min, on/off 5 min Temp. Change time 100min, DC Max Current	100 cycles	22
Temperature Cycle	-45°C / 15 min ↔ 125 °C / 15 min	200 cycles	100
High Temperature Storage	85 °C	1000 h	11
Low Temperature Storage	-40 °C	1000 h	11
ESD (HBM)	R <sub>1</sub> : 10 MΩ R <sub>2</sub> : 1.5 kΩ C: 100 pF V: ±2 kV	5 times	30

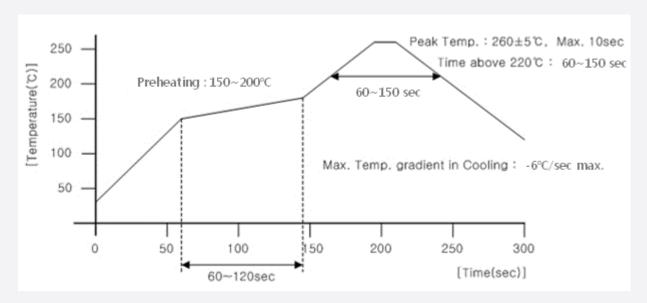
## b) Criteria for Judging the Damage

la con	Complete	Test Condition	Lim	it
ltem	Symbol	$(T_s = 25  ^{\circ}\text{C})$	Min	Max
Forward Voltage	V <sub>F</sub>	$I_F = 150 \text{ mA}$	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	2,	$I_F = 150 \text{ mA}$	Init. Value * 0.7	Init. Value * 1.1

## 6. Soldering Conditions

## a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.

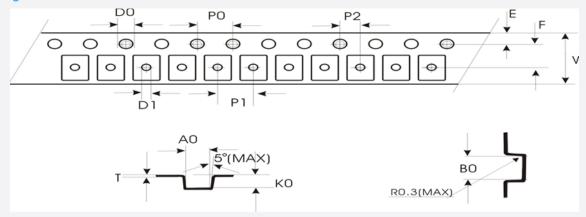


## b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.

## 7. Tape & Reel

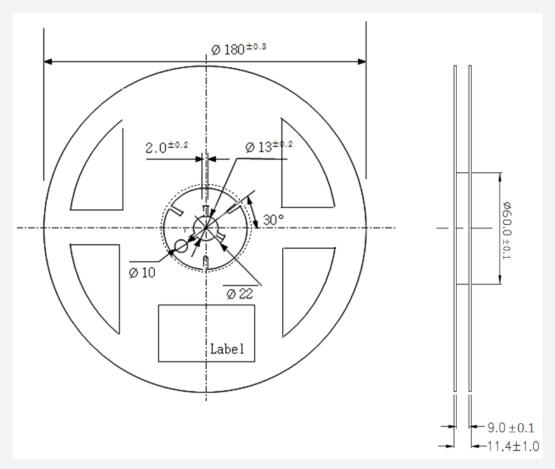
## a) Taping Dimension



A0	3.10±0.1	P0	4.00±0.1	Т	0.20±0.05	D0	1.60(MAX)
В0	3.70±0.1	P1	4.00±0.1	Е	1.75±0.1	D1	1.05(MIN)
K0	1.00±0.1	P2	2.00±0.1	F	3.50±0.05	V	8.00±0.1

## b) Reel Dimension (max 4,000 pcs)

(unit: mm)

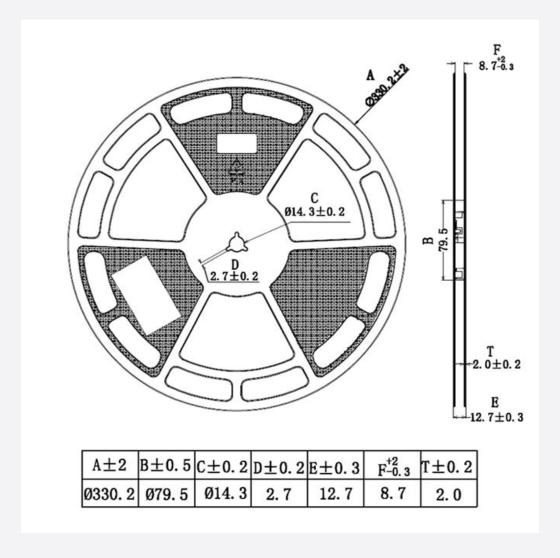


## Notes:

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) All dimensions are millimeters (tolerance: ±0.2mm)
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

## c) Reel Dimension (max 16,000 pcs)

(unit: mm)

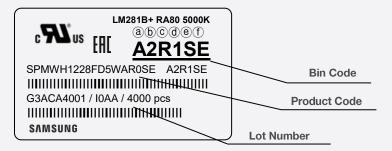


## Notes:

- 1) Quantity: The quantity/reel is 16,000 pcs
- 2) All dimensions are millimeters (tolerance: ±0.2mm)
- 3) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

#### 8. Label Structure

#### a) Label Structure



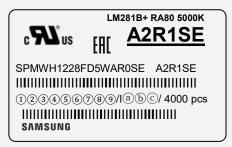
Note: Denoted bin code and product code above is only an example (see description on page 6)

#### Bin Code:

(a)(b): Forward Voltage bin (refer to page 10)(c)(d): Chromaticity bin (refer to page 11-18)(e)(f): Luminous Flux bin (refer to page 7)

## b) Lot Number

The lot number is composed of the following characters:



123456789 / Iabc / 4,000 pcs

①② : Production site (G3 or GP : Shenzhen, China)

③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

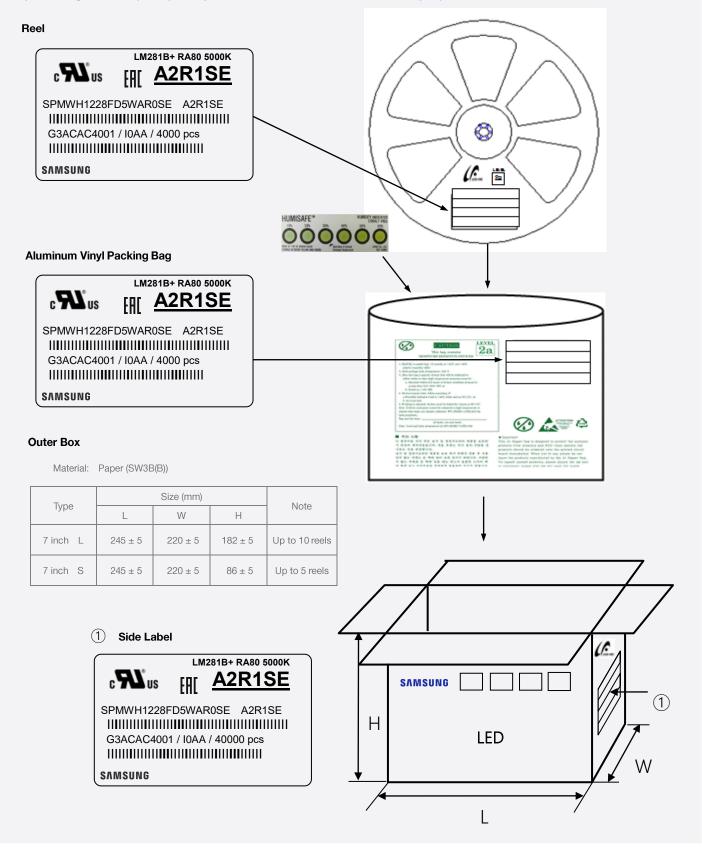
④ : Year (A: 2016, B: 2017, C: 2018, D: 2019, E: 2020...)

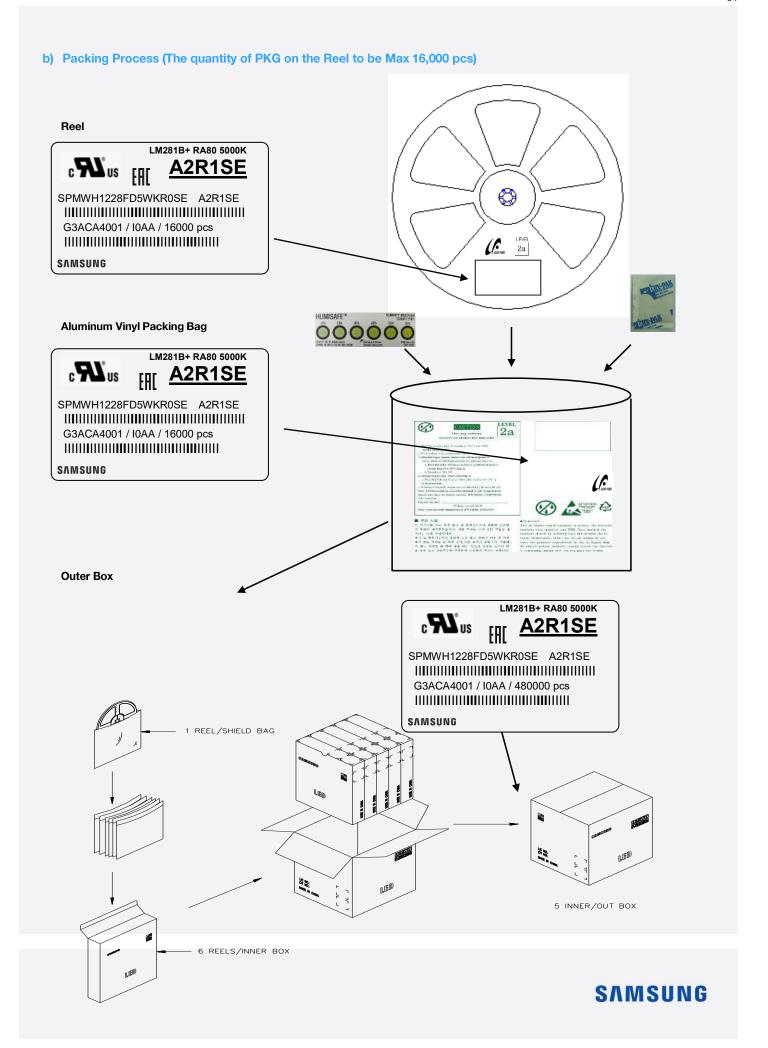
S : Month (1~9, A, B, C)
 6 : Day (1~9, A, B~V)

789 abc : Product serial number

## 9. Packing Structure







## c) Packing Process for kitting (The quantity of PKG on the Reel to be Max 4,000 pcs)

#### Reel

### Kitting 'A'

LM281B+ RA80 ★K c**su**us EAE A2★1SE

SPMWH1228FD5WA★KSE A2★1SE

..... G3ACA4001 / I0AA / 4000 pcs

SAMSUNG

### Kitting 'B'

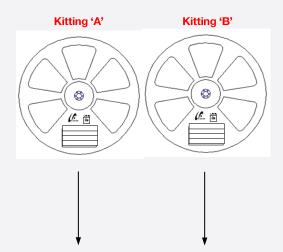
LM281B+ RA80 ★K c**FL**°us

EHE A2★CSE SPMWH1228FD5WA★KSE A2★CSE

......

G3ACA4001 / I0AA / 4000 pcs 

SAMSUNG



### **Aluminum Vinyl Packing Bag**

### Kitting 'A'

c **TL**us

LM281B+ RA80 ★K III A2★1SE

SPMWH1228FD5WA★KSE A2★1SE

G3ACA4001 / I0AA / 4000 pcs 

SAMSUNG

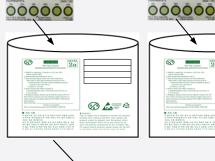
## Kitting 'B'

LM281B+ RA80 ★K c Wus ERE A2★CSE

SPMWH1228FD5WA★KSE A2★CSE

G3ACA4001 / I0AA / 4000 pcs 

SAMSUNG





## **Outer Box**

#### Kitting 'A'

LM281B+ RA80 ★K c**FL**°us EHE A2★1SE

SPMWH1228FD5WA★KSE A2★1SE

G3ACA4001 / I0AA / 20000 pcs

SAMSUNG [BOX Label] Kitting 'B'

LM281B+ RA80 ★K c **FL**°us III A2★CSE

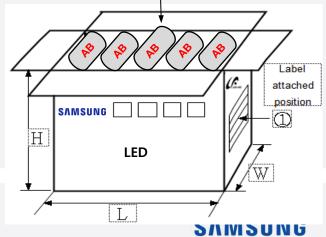
SPMWH1228FD5WA★KSE A2★CSE

G3ACA4001 / I0AA / 20000 pcs

SAMSUNG [BOX [BOX Label]

### Material: Paper (SW3B(B))

Type		Size (mm)	Note	
Туре	L	W	Н	Note
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels



## d) Packing Process for kitting (The quantity of PKG on the Reel to be Max 16,000 pcs)

#### Reel

### Kitting 'A'

LM281B+ RA80 ★K c**Sl**us EAL A2★1SE

SPMWH1228FD5WK★KSE A2★1SE

..... G3ACA4001 / I0AA / 16000 pcs

.....

SAMSUNG

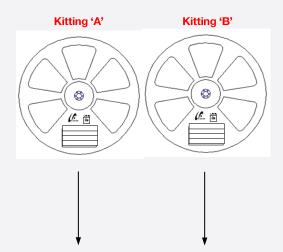
### Kitting 'B'

LM281B+ RA80 ★K c **Au**s III A2★CSE

SPMWH1228FD5WK★KSE A2★CSE

...... G3ACA4001 / I0AA / 16000 pcs 

SAMSUNG



## **Aluminum Vinyl Packing Bag**

### Kitting 'A'

LM281B+ RA80 ★K c **TL**us III A2★1SE

SPMWH1228FD5WK★KSE A2★1SE

G3ACA4001 / I0AA / 16000 pcs

SAMSUNG

### Kitting 'B'

LM281B+ RA80 ★K c**yll**us ERI A2★CSE

SPMWH1228FD5WK★KSE A2★CSE

G3ACA4001 / I0AA / 16000 pcs

SAMSUNG

## **Outer Box**

#### Kitting 'A'

LM281B+ RA80 ★K c**FL**°us III A2<u>★1SE</u>

SPMWH1228FD5WK★KSE A2★1SE

G3ACA4001 / I0AA / 80000 pcs

SAMSUNG

[BOX Label]

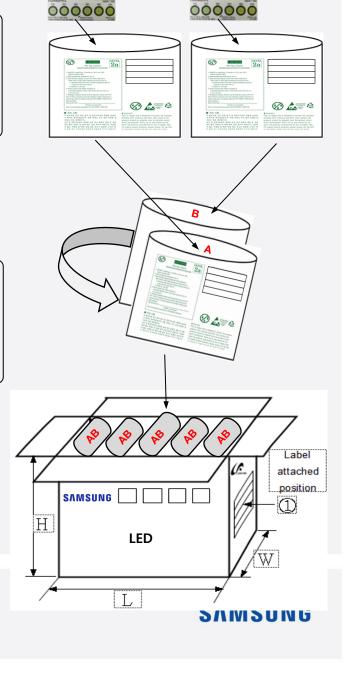
### Kitting 'B'

LM281B+ RA80 ★K c**su**s ERC A2★CSE SPMWH1228FD5WK★KSE A2★CSE G3ACA4001 / I0AA / 80000 pcs SAMSUNG [BOX

[BOX Label]

## Material: Paper (SW3B(B))

Type		Size (mm)	Note	
Туре	L	w	Н	Note
13 inch	378 ± 5	345 ± 5	405 ± 5	Up to 10 reels



#### e) Aluminum Vinyl Packing Bag



## CAUTION

# 2a

# This bag contains MOISTURE SENSITIVE DEVICES

- Shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- 2. Peak package body temperature: 240 °C
- After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
  - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C /60% RH, or
  - b. Stored at < 10% RH
- Devices require bake, before mounting, if:

   a. Humidity Indicator Card is > 60% when read at 23±5°C, or
   b. 2a is not met.
- 5. If baking is required, devices must be baked for 10 ~24 hours at 60±5°C Note: if device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure.

Bag seal due date:

(if blank, see code label)

Note: Level and body temperature by IPC/JEDEC J-STD-020

SAMSUNG





LM281B+ RA80 5000K

c ALUS [FI] A2R1SE

G3ACA4001 / I0AA / 4000 pcs



## ■ 주의 사항

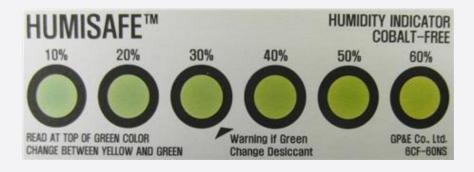
이 알루미늄 지퍼 백은 습기 및 정전기로부터 제품을 보호하 기 위하여 제작되었습니다. 개봉 후에는 즉시 솔더 작업을 설 시하는 것을 권장합니다.

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#### ■ Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products., please ensure the zip-lock is completely sealed with the dry pack left inside.

## f) Humidity Indicator Card inside Aluminum Vinyl Bag



## 10. Precautions in Handling & Use

- 1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- LEDs must be stored in a clean environment.
   (Shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- 5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be: a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH\*Note 1, or b. Mounted within 24 hours (1 day) at an assembly line with a condition of more than 30 °C / 70 % RH\*Note 2, or c. Stored at <10 % RH.

\*Note 1, 2: IPC/JEDEC J-STD-033A, Recommended Equivalent Total Floor Life Table

	Package Type and Body Thickness	Moisture Sensitivity	Maximum Percent Relative Humidity						Temperature
		Level							
Вос	D. d. Tribin	ness Level 2a	80	00	28	1	1	1	30°C
	Body Thickness <2.1mm		80	<b>6</b>		2	1	1	25℃
	2.111111		80	<b>6</b> 0	<b>6</b> 0	2	2	1	20°C

- 6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60 % at  $23 \pm 5 \degree$ C.
- 8) Devices must be baked for  $10\sim24$  hours at  $60\pm5$  °C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or antielectrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) Risk of sulfurization (or tarnishing)
  - The LED from Samsung uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.



# Legal and additional information.

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Samsung inspires the world and shapes the future with transformative ideas and technologies.

The company is redefining the worlds of TVs, smartphones, wearable devices, tablets, digital appliances, network systems, and memory, system LSI, foundry and LED

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